Solitec 1100 Spray Developer

User Guide

With Microposit 354 POSITIVE Photoresist Developer

Procedure

1. Control panel **POWER** switch ON (Fig. 1).
> **Note**: Do not adjust any controls on control panel.

2. **Vacuum pump switch** ON. (Fig. 2)
> **Note**: Vacuum gauge to rear of machine.

3. Use correct chuck for wafer on spindle. (Fig. 3)

4. Center wafer, face up, on chuck.

> **Note**: Developer temperature should be 19-21°C for good developing. (Digital indicator is located beneath flow meters).

5. Press **VAC** button (Fig. 3). Orange **VACUUM** indicator (Fig. 1) on control panel turns off.

6. Press and hold the START button (Fig 3), simultaneously lower the safety cover, until spray heads drop and wafer spins.

7. Allow developer, rinse, and spin dry cycles to complete.
> **Note**: If there is a problem press **STOP** button (Fig 3). Notify lab manager.

8. When cycles complete, manually raise the safety cover.

9. Press the **VAC** button (Fig 3) to release wafer vacuum.

10. Carefully remove wafer with tweezers.

11. Turn **vacuum pump switch** (Fig 1) OFF.

12. Hard-bake for several minutes at **90°C** (20 minutes is recommended) after developing in a bake oven to ensure a good quality photoresist pattern.

> **Tip: Under-developed** If the pattern is under-developed repeat the developing procedure once. In many cases, this will correct the problem.

Fig. 1 Control Panel
(DO NOT adjust any controls)

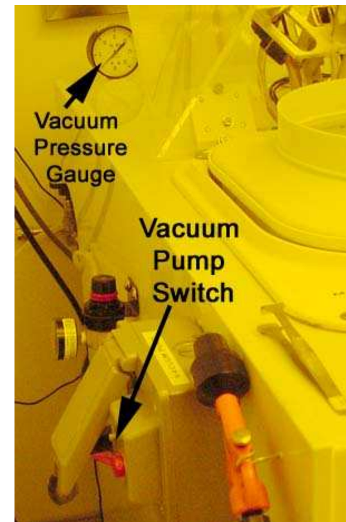

Fig. 2 Vacuum pump switch and pressure gauge

Fig. 3. Main controls

User Guide provided by TJ LaFave
updated February 17, 2004 (lafatim@iit.edu)